

CGJ4J3X7R1H474K125AB



**TDK item description** CGJ4J3X7R1H474KT\*\*\*\*

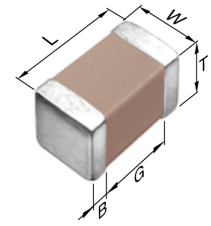
**Applications** High Reliability Grade

**Feature** General (Up to 50V)

AEC-Q200

**Series** CGJ4(2012) [EIA 0805]

**Status** Production



Dimensions in mm

**Size**

Length(L)	2.00mm ±0.20mm
Width(W)	1.25mm ±0.20mm
Thickness(T)	1.25mm ±0.20mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	1.00mm Min.
Recommended Land Pattern (PA)	1.00mm to 1.30mm(Flow Soldering)
	0.90mm to 1.20mm(Reflow Soldering)
Recommended Land Pattern (PB)	1.00mm to 1.20mm(Flow Soldering)
	0.70mm to 0.90mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.80mm to 1.10mm(Flow Soldering)
	0.90mm to 1.20mm(Reflow Soldering)

**Electrical Characteristics**

Capacitance	470nF ±10%
Rated Voltage	50VDC
Temperature Characteristic	X7R(±15%)
Dissipation Factor (Max.)	5%
Insulation Resistance (Min.)	1063MΩ

**Other**

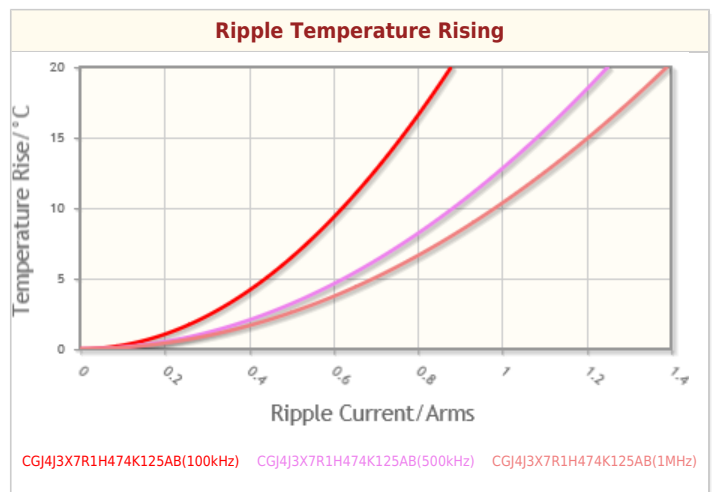
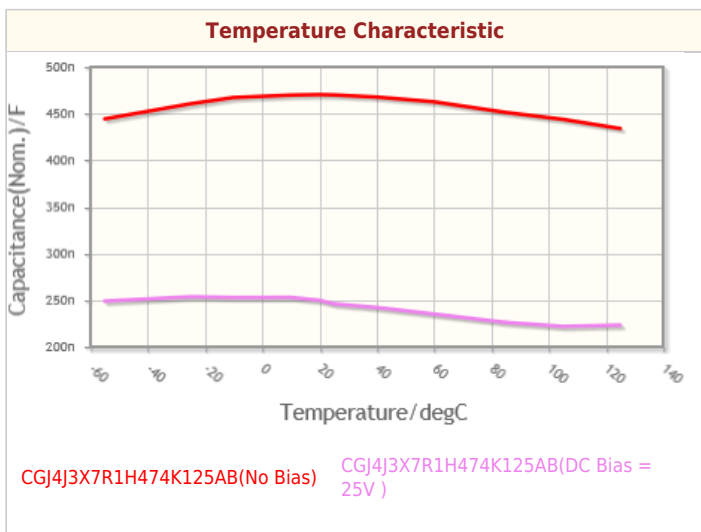
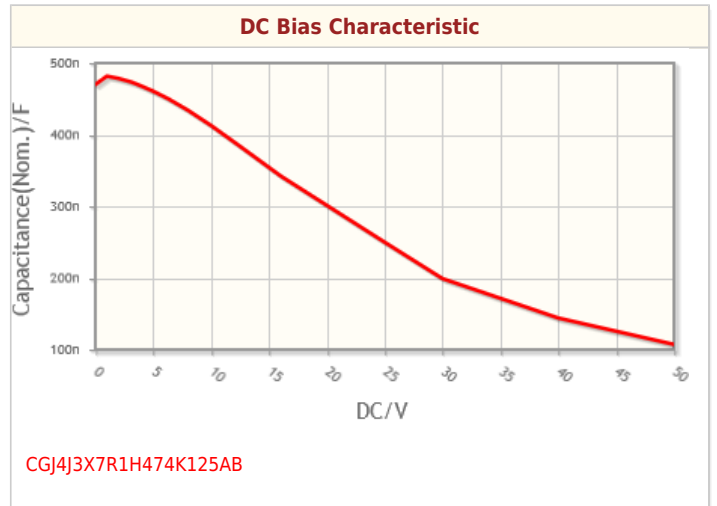
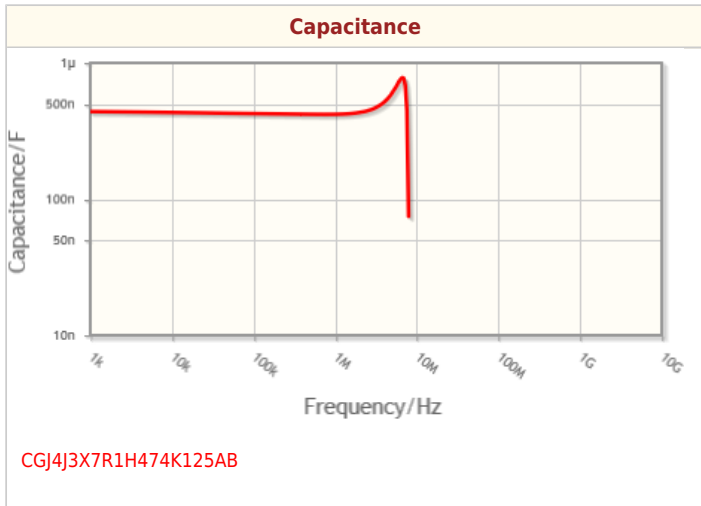
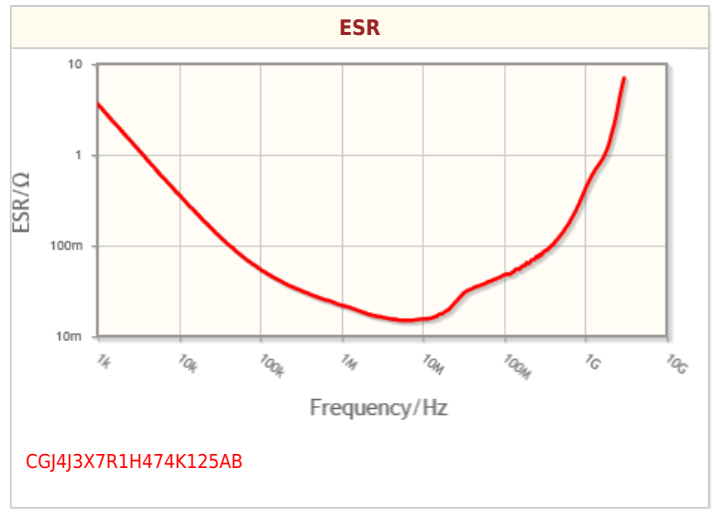
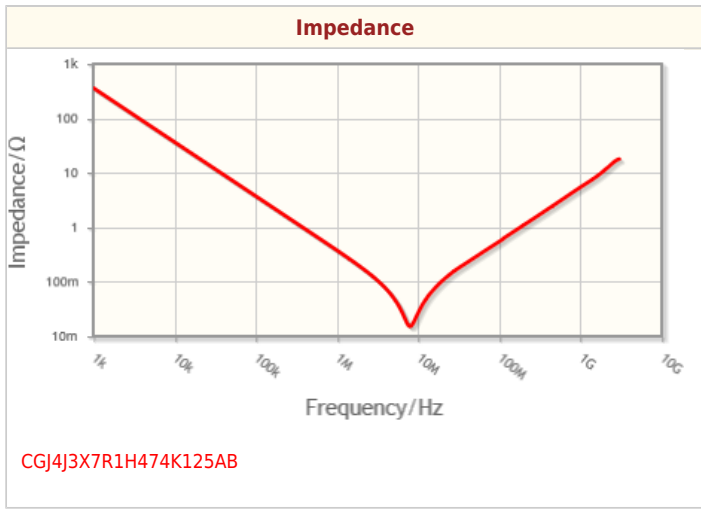
Soldering Method	Wave (Flow)
	Reflow
AEC-Q200	Yes
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	2000pcs

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! All specifications are subject to change without notice.

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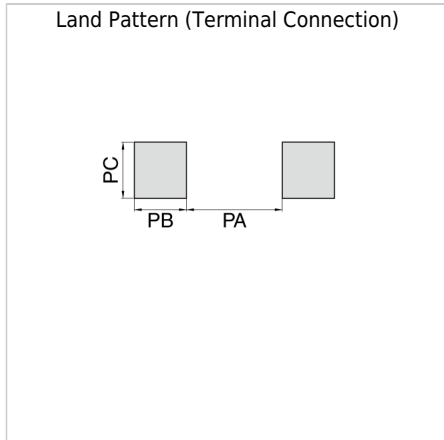
Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)



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## Associated Images



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